Reliability Data Report
Product Family R526

LTC3103 \ LTC3104 \ LTC3111 \ LTC3112 \ LTC3114 \ LTC3115 \ LTC3118 \ LTC3121 \ LTC3122 \ LTC3124 \ LTC3129 \ LTC3245 \ LTC3255 \ LTC3256 \ LTC3260 \ LTC3261 \ LTC3265 \ LTC3355 \ LTC3388 \ LTC3582 \ LTC3600 \ LTC3602 \ LTC3603 \ LTC3618 \ LTC3623 \ LTC3630 \ LTC3631 \ LTC3632 \ LTC3637 \ LTC3638 \ LTC3639 \ LTC3640 \ LTC3641 \ LTC3642 \ LTC3646 \ LTC3647 \ LTC3649 \ LTC3676 \ LTC3769 \ LTC3774 \ LTC3775 \ LTC3779 \ LTC3784 \ LTC3786 \ LTC3787 \ LTC3788 \ LTC3789 \ LTC3790 \ LTC3807 \ LTC3829 \ LTC3833 \ LTC3838 \ LTC3839 \ LTC3850 \ LTC3851 \ LTC3852 \ LTC3853 \ LTC3854 \ LTC3855 \ LTC3856 \ LTC3857 \ LTC3858 \ LTC3859 \ LTC3862 \ LTC3863 \ LTC3864 \ LTC3865 \ LTC3866 \ LTC3867 \ LTC3868 \ LTC3869 \ LTC3870 \ LTC3871 \ LTC3874 \ LTC3875 \ LTC3876 \ LTC3877 \ LTC3878 \ LTC3879 \ LTC3880 \ LTC3882 \ LTC3883 \ LTC3884 \ LTC3886 \ LTC3887 \ LTC3890 \ LTC3891 \ LTC3892 \ LTC3895 \ LTC3896 \ LTC3897 \ LTC3899 \ LTC7101 \ LTC7103 \ LTC7801 \ LTC7804 \ LTC7818 \ LTC7852
## OPERATING LIFE TEST

<table>
<thead>
<tr>
<th>PACKAGE TYPE</th>
<th>SAMPLE SIZE</th>
<th>OLDEST DATE CODE</th>
<th>NEWEST DATE CODE</th>
<th>K DEVICE HRS (+125°C)</th>
<th>No. of FAILURES</th>
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<tbody>
<tr>
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## HIGHLY ACCELERATED STRESS TEST AT +130 DEG C / 85% RH

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<th>OLDEST DATE CODE</th>
<th>NEWEST DATE CODE</th>
<th>K DEVICE HRS (+85°C)</th>
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## PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C

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<th>K DEVICE HRS</th>
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## TEMP CYCLE FROM -65 TO 150 DEG C

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<th>K DEVICE CYCLES</th>
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(1) Assumes Activation Energy = 0.7 Electron Volts
(2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =0.32 FITS
(3) Mean Time Between Failure in Years = 356298.62
(4) Assumes 20X Acceleration from 85 °C to +130 °C
(5) Assumes 20X Acceleration from 85 °C to +130 °C
(6) Assumes 20X Acceleration from 85 °C to +130 °C
Note 1: 1 FIT = 1 Failure in One Billion Hours.
Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL Preconditioning
## Reliability Data Report
**Report Number: R526**
Report generated on: Fri Apr 10 15:42:31 PDT 2020

### TEMP CYCLE FROM -40 TO 125 DEG C

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<th>K DEVICE CYCLES</th>
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### THERMAL SHOCK FROM -65 TO 150 DEG C

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### HIGH TEMPERATURE BAKE AT 125 DEG C

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### HIGH TEMPERATURE BAKE AT 150 DEG C

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### HIGH TEMPERATURE BAKE AT 175 DEG C

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